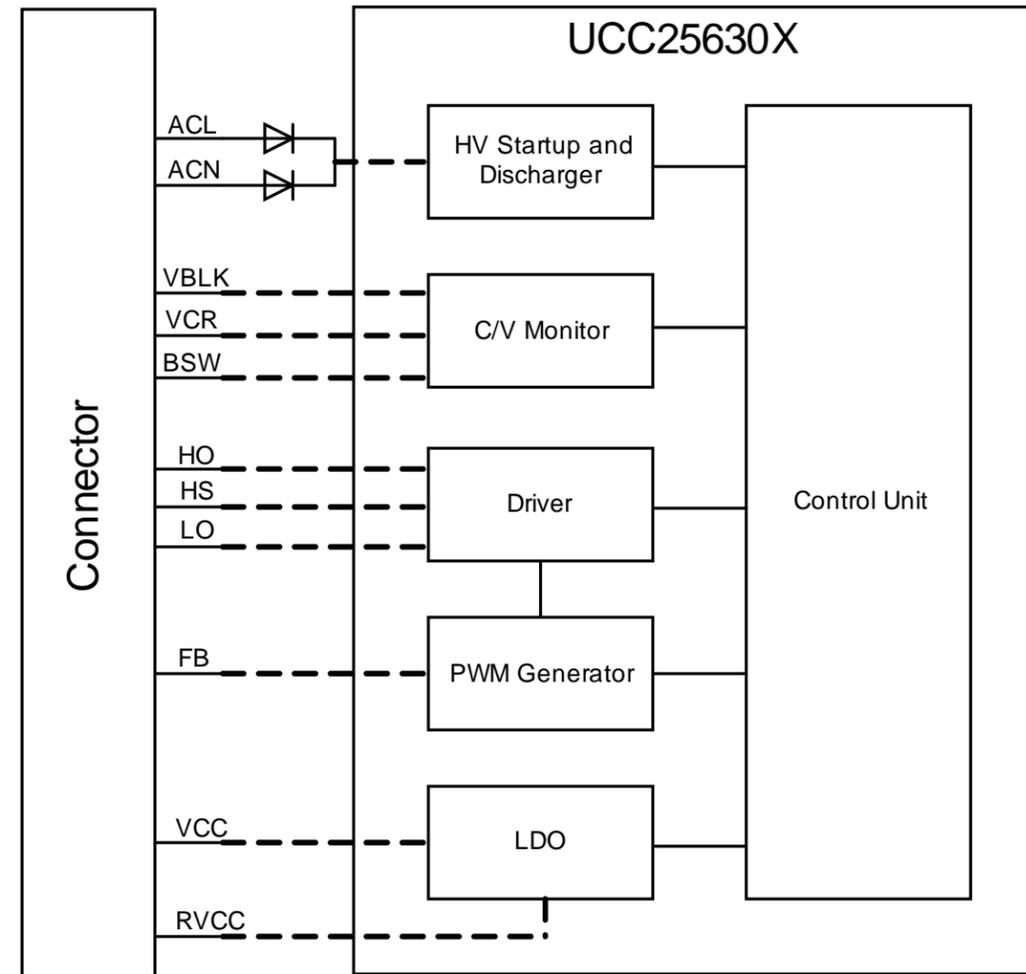


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 8/17/2017
TID #: PMP40281	Project Title: UCC25630X Daughter Card	
Number: PMP40281	Rev: 1.0	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP40281_CoverSheet.SchDoc	Size: B
Engineer: Yingyang Ou	Contact: http://www.ti.com/support	http://www.ti.com



PCB
LOGO
Pb-Free Symbol

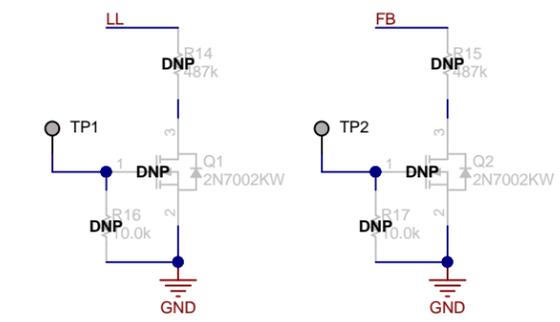
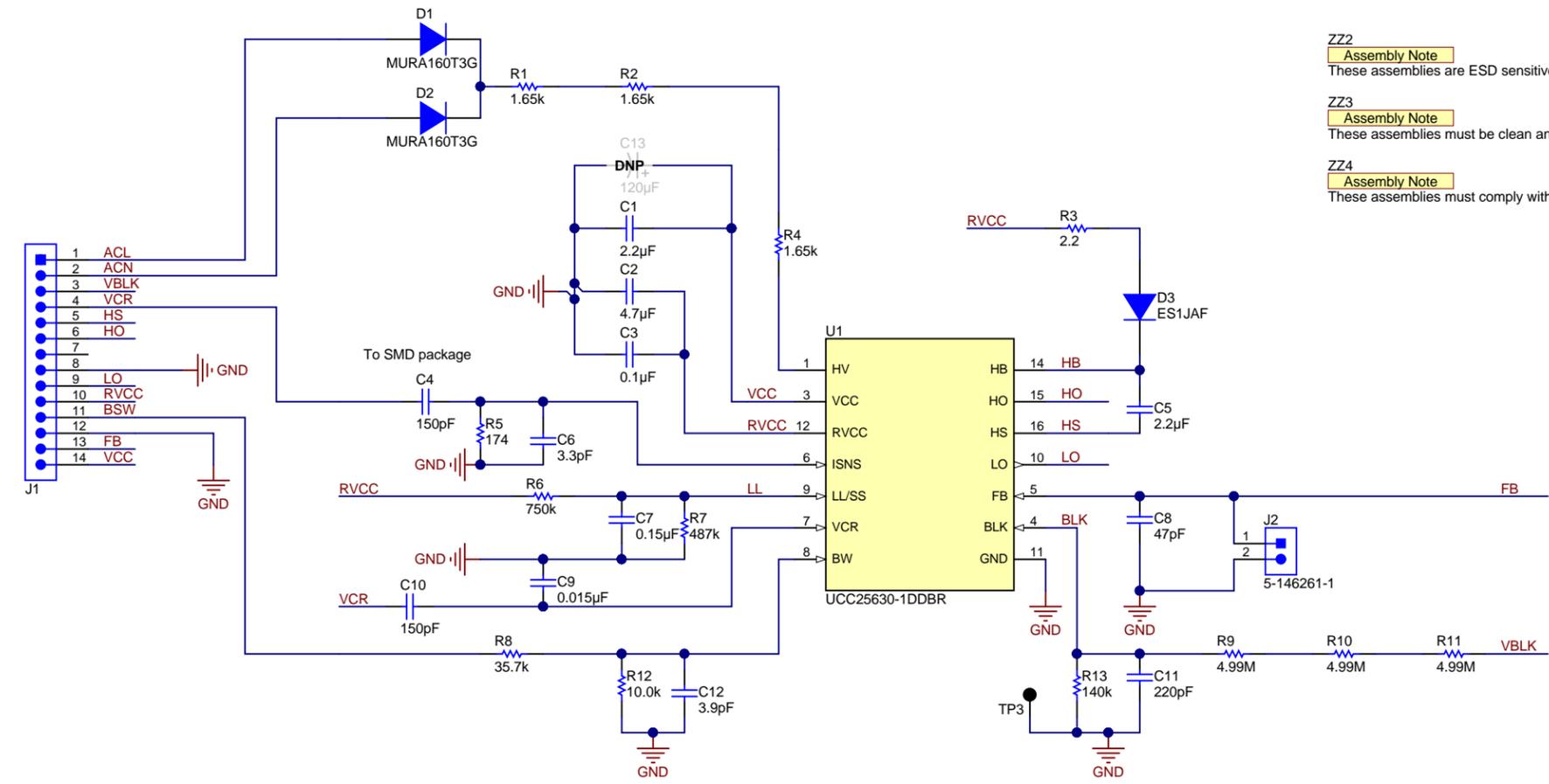


ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 8/4/2017	
TID #: PMP40281	Project Title: UCC25630X Daughter Card	Sheet: 2 of 2	
Number: PMP40281	Rev: 1.0	Sheet Title:	http://www.ti.com © Texas Instruments 2017
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By:	File: PMP40281_Main.SchDoc	Contact: http://www.ti.com/support	
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